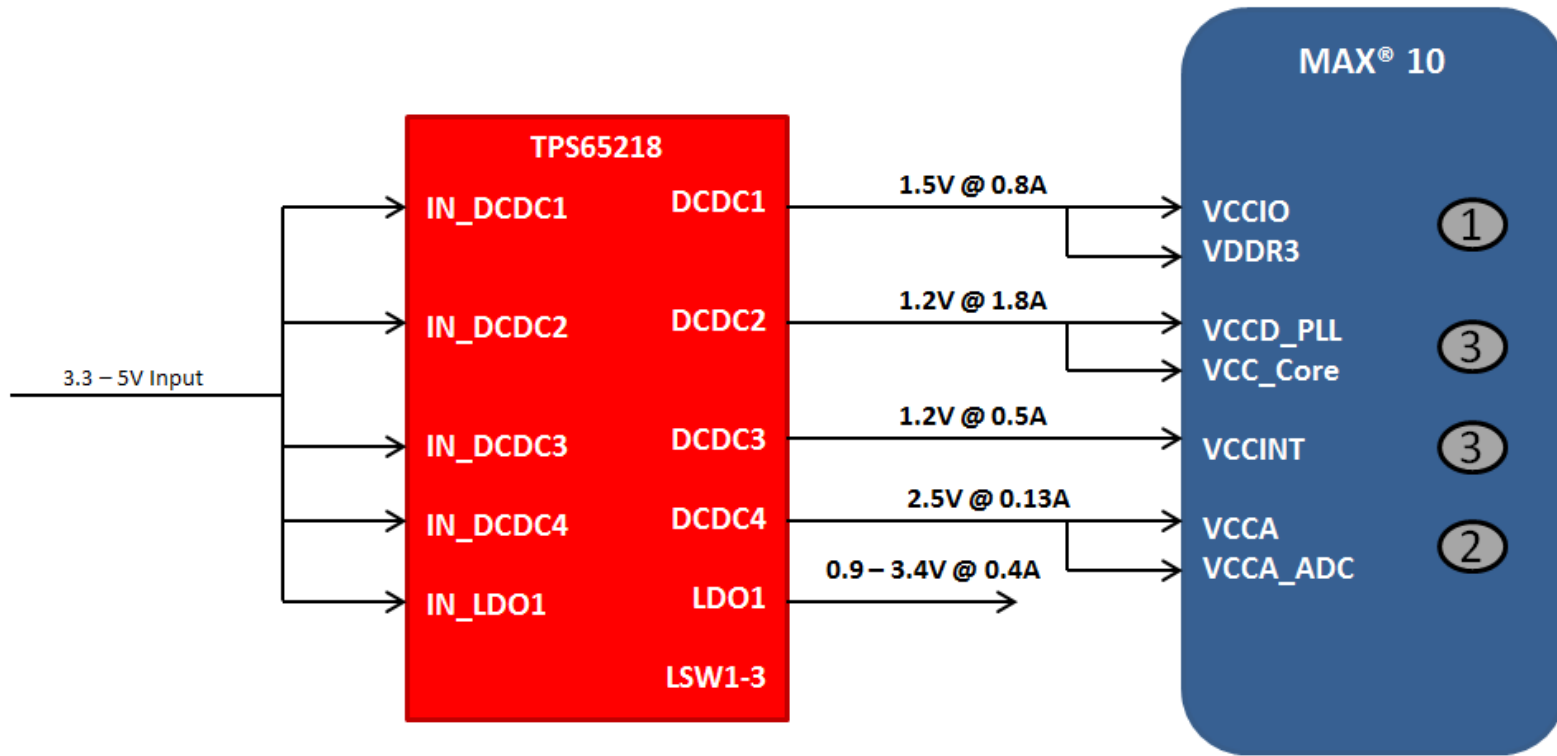


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A

## Altera® MAX® 10 TPS65218 Block Diagram



(X) = Power Sequencing Order

A

B

C

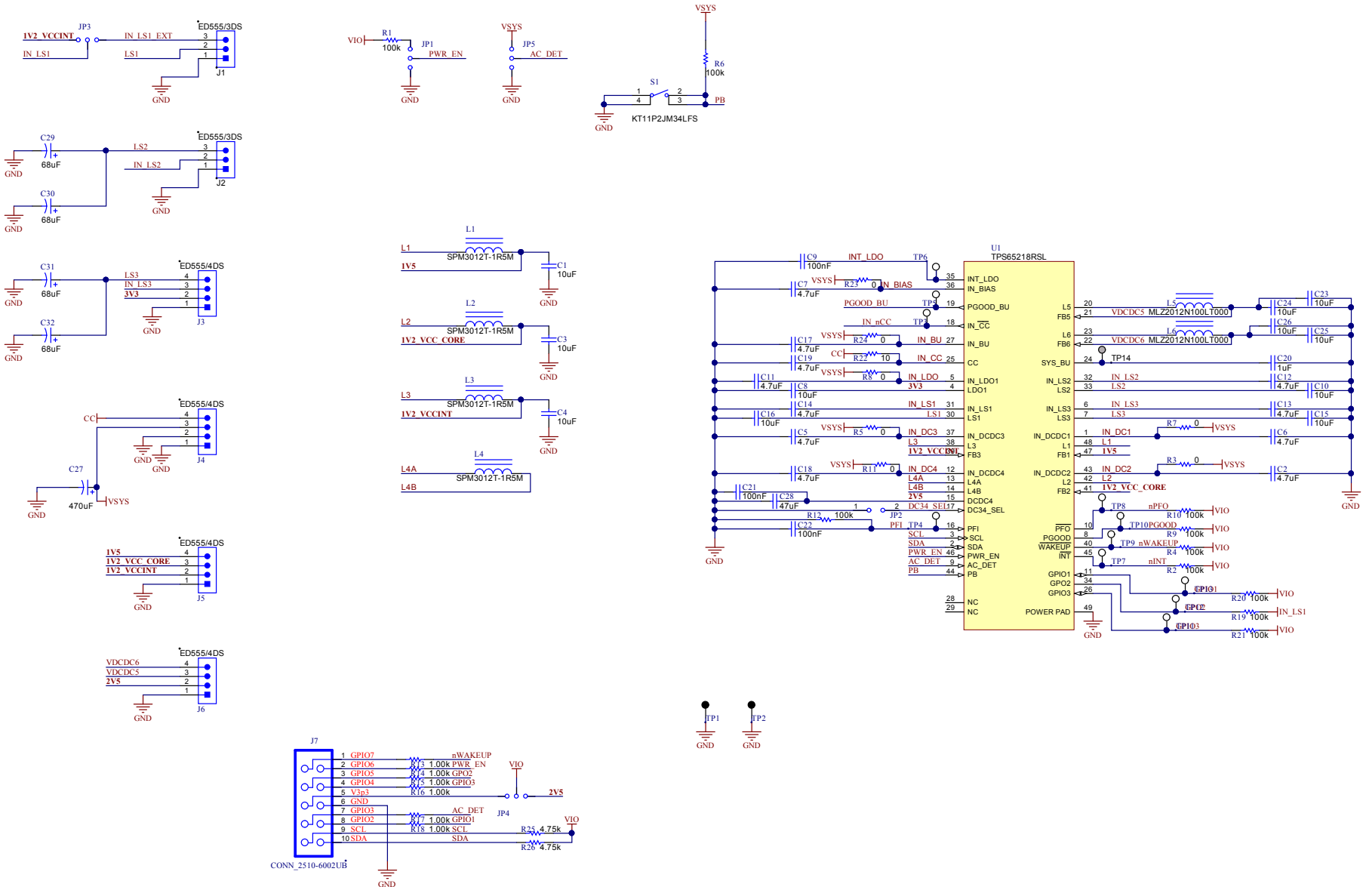
D

A

B

C

D



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Number: TIDA-00607   Rev: E1	Sheet Title:	Sheet 2 of 3
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	
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